Results on FBK 3D pixel detectors for CMS

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CMS-TOTEM Proton Precision Spectrometer



3D silicon sensors

3D silicon detectors were proposed in 1997 by Parker, Kenney and Segal.



Possibility to implement active edges.

3D sensors have electrodes that are etched perpendicular through the silicon bulk.



The architecture decouples substrate thickness and electrode distance. The result is the same charge deposit of a planar silicon sensor of the same thickness but electrode distances strongly reduced.

Columns have radius of ~ 5 μm and the distance between electrodes varies from 100 μm to 50 μm depending on the pixel configuration.



Tested FBK 3D sensors





Double-Sided Full 3D



Columns etched in the substrate determine a geometrical inefficiency for tracks entering the detector perpendicularly to the surface. Tilting the detector is necessary for increasing the efficiency.

FBK 3D testing steps

March 2014:

- 10 FBK 3D sensors bump-bonded to the CMS pixel digital ReadOut Chip (ROC).
- IV curve measurements and ROC optimisation and calibration in Torino.

April 2014:

 7 good quality detectors tested with 120 GeV protons at Fermi National Accelerator Laboratory (FNAL).

June 2014:

8 detectors irradiated with 23 MeV protons at Karlsruhe Institute of Technology (KIT) within the AIDA project, at fluences of 1-3-6-10x10¹⁵ n_{eq}/cm² (corresponding dose: 150-450-900-1500 Mrad).

July 2014:

at Torino laboratory:

- IV curve measurements
- Setting and calibration of survived ROCs (1- $3x10^{15} n_{eq}/cm^2$)

August 2014:

Irradiated detectors tested on beam at FNAL.

IV curves before and after irradiation

Before irradiation:

- IV measured at room temperature.
- 7 sensors show a breakdown voltage higher than 30 V as expected.



100

150

200

250 bias voltage [-V]

After irradiation:

- IV measured at -12°C, same temperature used at the testbeam.
- Increase of breakdown voltage due to charge created by the irradiation on the sensor surface.
- Leakage currents are in agreement with the Atlas IBL 3D ones.

Testbeam at FNAL (T992 collaboration)



- 8 telescope planes of CMS pixel modules (pixel size 100x150 µm²), 4 upstream and 4 downstream with respect to the DUTs
- Telescope planes rotated of 25° with respect to 100 µm pixel pitch direction for increasing resolution to 8 µm
- Rotation and cooling systems for the DUTs provided by Purdue
- Alignment and analysis software developed at Milano Bicocca



Efficiency vs bias (angle 0°)

efficiency

Preliminary

Testing procedure:

- Threshold scan
- Bias Scan
- Angle Scan

Before irradiation:

- Threshold between ~2500-3000 e⁻
- Efficiency saturation already at 5 V
- Bias voltage between 25 V and 30 V chosen for angle scan



Efficiency vs Bias After Irradiation

After irradiation:

- Threshold ~3000 e⁻ for FBK_11_37_01 and FBK_11_37_02.
- Threshold ~4700 e⁻ for FBK_11_43_01 due to ROC problems.
- Sensors forced into breakdown region to try to reach full depletion



Pixel cell efficiency after irradiation

FBK_11_37_01 (1x10¹⁵ n_{eq}/cm²)





1 readout column not enough to fully collect charge in the side regions



Cell charge before irradiation



Cell charge after irradiation

FBK_11_37_01 (1x10¹⁵ n_{eq}/cm²)

Charge vs bias (angle 0°)





Cluster size before and after irradiation

Before Irradiation

Cluster Size 2 Probability vs Bias Before Irradiation



Cluster Size 2 Probability vs Angle Before Irradiation



Preliminary Cluster Size 2 Probability vs Bias After Irradiation

After Irradiation



Cluster Size 2 Probability vs Angle After Irradiation



Residuals plots



FBK_11_37_01: X Residuals Cluster Size 2 Calculated Bias 30



- Residuals cluster size 1 fitted with a square function convoluted with a gaussian.
- Residuals cluster size 2 "Calculated" evaluated by the charge asymmetry and fitted with a gaussian.
- Residuals cluster size 2 "Digital" evaluated assuming that the particle crosses the sensor exactly of to the border of the two hit pixels and fitted with a gaussian.





 $\sigma_{\rm CS2} = \sqrt{sigma_{\rm CS2}^2 - sigma_{\rm telescope}^2}$

Resolution before irradiation



X Residuals Cluster Size 2 Sigma Calculated vs Angle Before Irradiation



X Residuals Cluster Size 2 Sigma Digital vs Angle Before Irradiation



Resolution after irradiation



Conclusions

- FBK 1E 3D sensors bump-bonded to the CMS digital ROCs have been tested successfully before and after irradiation. Preliminary results have been shown.
- Efficiency before irradiation > 99.5% at angle > 5° .
- Efficiency after irradiation > 98% at 20° after irradiation of $1 \times 10^{15} n_{eq}/cm^2$.
- Cluster size 2 probability behaviour as a function of bias and angle as expected before irradiation. Low statistic after irradiation due to not full depletion of the pixel borders.
- Resolutions before irradiation at 20°: ~28 μ m for cluster size 1 and ~8 μ m for cluster size 2.
- All the limitations in terms of efficiency and resolution are expected to be overcome using sensors with more than one readout column in each pixel.

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Backup Slides

FBK 3D + CMS analog chip efficiency



A. Krzywda et al., NIM A 763 (2014) 404-411

Pixel cell efficiency after irradiation

FBK_11_37_02 (3x10¹⁵ n_{eq}/cm²)

Preliminary



150 *µ*m

Cell charge after irradiation

FBK_11_37_02 (3x10¹⁵ n_{eq}/cm²)



Cell cluster size before irradiation



ona pitch (um)

reasons.

long pitch (um)

long pitch (um)

Edge efficiency before irradiation



At operating voltage and angle of 20°: extra ~70 μ m of active area at sensor edge